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08-07-2001

HEET

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Patent and Trademark Office



101802609

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To the Honorable Commissioner of F

record the attached original documents or copy thereof.

1. Name of conveying party(ies):

CHUNG, Seung-Pil
CHI, Kyeong-Koo
JEON, Jung-Sik

7-30-01

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRONICS CO., LTD.

Address: 416, Maetan-dong, Paldal-gu,

11002 U.S. PTO
09/916319
07/30/01

Additional names(s) of conveying party(ies) Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

City: Suwon-city, Kyungki-do State/Prov.:

Country: Republic of Korea ZIP:

Execution Date: July 12, 2001

Additional name(s) & address(es) Yes No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: July 12, 2001

Patent Application No. Filing date

B. Patent No.(s)

08/01/2001 HNHCHH1 00000003 09916319

JULY 30, 2001

NEW
02 FC:581

Additional numbers

Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ADAM C. VOLENTINE

Registration No. 33289

Address: JONES VOLENTINE, PLLC

12200 SUNRISE VALLEY DRIVE, SUITE 150

City: RESTON

State/Prov.: VA

Country: U.S.A.

ZIP: 20191

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

Authorized to be charged to deposit account

8. Deposit account number:

50-0238

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ADAM C. VOLENTINE

Name of Person Signing

Signature

JULY 30, 2001

Date

3

Total number of pages including cover sheet, attachments, and

PATENT

REEL: 012031 FRAME: 0136

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s)

CHUNG, Seung-Pil

CHI, Kyeong-Koo

JEON, Jung-Sik

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)
of Assignee(s)

SAMSUNG ELECTRONICS CO., LTD.

Address

of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention

METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE HAVING CONTACT PADS

for which an application for patent in the United States of America has been executed by the undersigned

Date of Signing
of Application

on July 12, 2001

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289, and the firm of JONES VOLENTINE, P.L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date July 12, 2001, Name of Inventor Seung-Pil Chung
Seung-Pil CHUNG

Date July 12, 2001, Name of Inventor Kyeong-Koo Chi
Kyeong-Koo CHI

Date July 12, 2001, Name of Inventor Jung-Sik Jeon
Jung-Sik JEON

Date _____, Name of Inventor _____

Date _____, Name of Inventor _____

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness _____

Witness _____

ACKNOWLEDGMENT

_____ } ss

This _____ day of _____, 19____, before me personally came the above-named _____

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature

Official Title

SEAL

Applicant Reference No.: IE10188-US Atty Docket No.: SEC.849

Serial No.: _____ Filing Date: _____